

WHAT IS CLAIMED IS:

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1. A sealed semiconductor device comprising semiconductor chip portions and a lead frame portion including internal lead portions extending on surfaces of the semiconductor chip portions, wherein holding members are included which hold said semiconductor chip portions and said internal lead portions at predetermined intervals by being fixed to either of said semiconductor chip portions and said internal lead portions but not being fixed to the other.

2. The sealed semiconductor device according to claim 1, wherein said holding members include a tape member bonded and fixed to said internal lead portion.

3. The sealed semiconductor device according to claim 2, wherein said tape member is set so as to be located in areas peripheral said semiconductor chip portions.

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4. The sealed semiconductor device according to claim 1, wherein said holding members include first protrusions protruding toward said semiconductor chip portions provided to said internal lead portions.

5. The sealed semiconductor device according to claim 4, wherein said first protrusions are formed by bending said internal lead portions.

6. The sealed semiconductor device according to claim 5, wherein crest portions of said internal leads formed by being bent contact with said semiconductor chip portions.

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7. The sealed semiconductor device according to claim 4, wherein said internal lead portions include an original internal lead electrically connected with said semiconductor chip portions and dummy internal leads, and

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said first protrusions are formed on said dummy internal lead portions.

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8. The sealed semiconductor device according to claim 7, wherein said semiconductor chip portions are almost rectangular, and said original internal lead is set toward a pad portion formed nearby centers of said rectangular semiconductor chip portions from a pair of faced sides of said semiconductor chip portions, said dummy internal leads are arranged toward the semiconductor chip portions from the other pair of sides facing the direction almost orthogonal to said pair of faced sides,

9. The sealed semiconductor device according to claim 4, wherein said first protrusions contact with areas peripheral to said semiconductor chip portions.

10. The sealed semiconductor device according to claim 9, wherein said semiconductor chip portions include a semiconductor chip body and a die pad for mounting said semiconductor chip body, and said first protrusions contact with said die pad.

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11. The sealed semiconductor device according to claim 1, wherein said semiconductor chip portions include a semiconductor chip body and a die pad for mounting said semiconductor chip body, and said holding members include second protrusions fixed to said die pad and protruding toward said internal leads.

12. The sealed semiconductor device according to claim 1, wherein said holding members are formed so as to be at least located at the opposite side to an injection port of a mold resin when sealing said semiconductor chip portions and said internal lead portions with a mold resin.

13. A lead frame used for a sealed semiconductor device obtained by

sealing semiconductor chip portions with a mold resin, comprising:
an internal lead portion set toward a pad portion formed nearby the
center of said semiconductor chip portions and electrically connected with
said pad portion; and
holding lead portions for holding said semiconductor chip portions
and said internal lead at predetermined intervals by contacting with said
semiconductor chip portions.

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14. The lead frame according to claim 13, wherein
said holding lead portions include said internal lead portion, and
a tape member is bonded and fixed to said holding lead portions at
positions corresponding to areas peripheral to said semiconductor chip
portions.

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15. The lead frame according to claim 13, wherein said holding lead
portions are dummy internal lead portions.

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16. The lead frame according to claim 15, wherein
said internal lead portion is set toward said pad portion of almost-
rectangular semiconductor chip portions from a pair of faced sides of the
almost-rectangular semiconductor chip portions, and
said holding lead portions are arranged toward said semiconductor
chip portions from the other pair of sides facing the direction almost
orthogonal to said pair of faced sides.